

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS1230AB	Jul-96	9619 H	DALLAS	DA079619AAA	N/A	28 MODULE

STRESS/JOB NO.

**READPOINT
(Sample Size/No. of Fails)**

Storage Life
85°C, No Bias
P-17808

<u>48 Hr</u>	<u>Cum %</u>
200/0	0.0%

Temp Cycle
0°C to +70°C
P-17872

<u>300 ~</u>	<u>1K ~</u>	<u>Cum %</u>
100/0	100/0	0.0%

Moisture Soak
60°C/90% RH
P-17873

<u>274 Hr</u>	<u>959 Hr</u>	<u>Cum %</u>
100/0	100/0	0.0%

Phys. Dimen.
P-17807
6/0

Solderability
P-17806
24/5
F1

Failure Mode

F1: 5-Dewetting

Failure Analysis

Epoxy on leads